

Vishay Semiconductors

AAP Gen 7 (TO-240AA) Power Modules Thyristor/Diode and Thyristor/Thyristor, 45 A, 60 A



ADD-A-PAK

PRIMARY CHARACTERISTICS						
$I_{T(AV)}$ or $I_{F(AV)}$	45 A, 60 A					
Type	Modules - thyristor, standard					
Package	AAP Gen 7 (TO-240AA)					

MECHANICAL DESCRIPTION

The AAP Gen 7 (TO-240AA), new generation of AAP module, combines the excellent thermal performances obtained by the usage of exposed direct bonded copper substrate, with advanced compact simple package solution and simplified internal structure with minimized number of interfaces.

FEATURES

- · High voltage
- · Industrial standard package
- Low thermal resistance
- UL approved file E78996
- · Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

BENEFITS

- Excellent thermal performances obtained by the usage of exposed direct bonded copper substrate
- Up to 1600 V
- · High surge capability
- Easy mounting on heatsink

ELECTRICAL DESCRIPTION

These modules are intended for general purpose high voltage applications such as high voltage regulated power supplies, lighting circuits, temperature and motor speed control circuits, UPS, and battery charger.

MAJOR RATIN	IGS AND CHARACTERISTI	ICS			
SYMBOL	CHARACTERISTICS	VS-VSK.41	VS-VSK.56	UNITS	
I _{T(AV)} or I _{F(AV)}	85 °C	45	60		
I _{O(RMS)}	As AC switch	100	135	А	
I _{TSM} ,	50 Hz	850	1200		
I _{FSM}	60 Hz	890	1256		
l ² t	50 Hz	3.61	7.20	kA ² s	
1-1	60 Hz	3.30	6.57		
I²√t		36.1	72	kA²√s	
V _{DRM} /V _{RRM}	Range	400 to 1600	400 to 1600	V	
T _{Stg}		-40 to +125		°C	
T _J		-40 to	o +125	°C	



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ELECTRICAL SPECIFICATIONS

VOLTAGE RA	ATINGS				
TYPE NUMBER	VOLTAGE CODE	V _{RRM} , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	V _{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	V _{DRM} , MAXIMUM REPETITIVE PEAK OFF-STATE VOLTAGE, GATE OPEN CIRCUIT V	I _{RRM,} I _{DRM} AT 125 °C mA
	04	400	500	400	
	06	600	700	600	
VC VCK 41	08	800	900	800	
VS-VSK.41 VS-VSK.56	10	1000	1100	1000	15
VO VOIX.50	12	1200	1300	1200	
	14	1400	1500	1400	
	16	1600	1700	1600	

ON-STATE CONDUCTION								
PARAMETER	SYMBOL	1	EST CONDITION	ONS	VSK.41	VSK.56	UNITS	
Maximum average on-state current (thyristors)	I _{T(AV)}	180° conduction, half sine wave,		on, half sine wave,		60		
Maximum average forward current (diodes)	I _{F(AV)}	T _C = 85 °C	T _C = 85 °C		45	60		
Maximum continuous RMS on-state current, as AC switch	I _{O(RMS)}	or I(RMS)		100	135	A		
		t = 10 ms	No voltage	Sinusoidal	850	1200		
Maximum peak, one-cycle non-repetitive	I _{TSM}	t = 8.3 ms	reapplied	half wave,	890	1256		
on-state or forward current	or I _{FSM}	t = 10 ms	100 % V _{RRM}	initial T _J =	715	1000		
	·F3W	t = 8.3 ms	reapplied	T _J maximum	750	1056		
		t = 10 ms	No voltage		3.61	7.20	kA ² s	
Maximum I ² t for fusing	l ² t	t = 8.3 ms	reapplied	Initial T _J =	3.30	6.57		
	I-t	t = 10 ms	100 % V _{RRM}	T _J maximum	2.56	5.10		
		t = 8.3 ms	reapplied		2.33	4.56		
Maximum I ² √t for fusing	I ² √t ⁽¹⁾	t = 0.1 ms to 10 $T_J = T_J \text{ maximu}$	10 ms, no voltage reapplied		36.1	72	kA²√s	
Maximum value or threehold valtage	V (2)	Low level (3)	T T		1.08	0.91	.,	
Maximum value or threshold voltage	V _{T(TO)} (2)	High level (4)	$T_J = T_J \text{ maxin}$	lum	1.12	1.02	- V	
Maximum value of on-state	r _t ⁽²⁾	Low level (3)	T T mayin		4.7	4.27	~ 0	
slope resistance	't (-)	High level (4)	$T_J = T_J$ maximum		4.5	3.77	mΩ	
Maximum pools on state or femurard voltage	V _{TM}	$I_{TM} = \pi \times I_{T(AV)}$	T 05.00		1.81	1.7	W	
Maximum peak on-state or forward voltage	V _{FM}	$I_{FM} = \pi \times I_{F(AV)}$	$T_J = 25 ^{\circ}C$		1.01	1.7	V	
Maximum non-repetitive rate of rise of turned on current	dl/dt	$T_J = 25$ °C, from 0.67 V_{DRM} , $I_{TM} = \pi \times I_{T(AV)}$, $I_g = 500$ mA, $t_r < 0.5$ μ s, $t_p > 6$ μ s		1	50	A/µs		
Maximum holding current	I _H	T _J = 25 °C, anode supply = 6 V, resistive load, gate open circuit			20	00	mA	
Maximum latching current	ΙL	T _J = 25 °C, and	ode supply = 6 \	/, resistive load	400	400		

Notes

⁽¹⁾ I^2t for time $t_x = I^2\sqrt{t} \ x \ \sqrt{t_x}$

⁽²⁾ Average power = $V_{T(TO)} \times I_{T(AV)} + r_t \times (I_{T(RMS)})^2$

^{(3) 16.7 %} x π x I_{AV} < I < π x I_{AV}

 $^{^{(4)}~}I>\pi~x~I_{AV}$



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TRIGGERING							
PARAMETER	SYMBOL	TEST CONDITIONS		VS-VSK.41	VS-VSK.56	UNITS	
Maximum peak gate power	P _{GM}			1	0	W	
Maximum average gate power	P _{G(AV)}			2	.5	VV	
Maximum peak gate current	I _{GM}			2	.5	Α	
Maximum peak negative gate voltage	- V _{GM}			1	0		
	V _{GT}	T _J = -40 °C	Anode supply = 6 V resistive load	4.0		V	
Maximum gate voltage required to trigger		T _J = 25 °C		2	.5	v	
		T _J = 125 °C		1	.7		
		T _J = -40 °C		2	70		
Maximum gate current required to trigger	I _{GT}	T _J = 25 °C	Anode supply = 6 V resistive load	15	150		
		T _J = 125 °C	Toolotive load	8	0		
Maximum gate voltage that will not trigger	V_{GD}	T _J = 125 °C, rated V _{DRM} applied		0.	25	V	
Maximum gate current that will not trigger	I _{GD}	T _J = 125 °C, rated	V _{DRM} applied	(3	mA	

BLOCKING							
PARAMETER	SYMBOL	TEST CONDITIONS	VS-VSK.41	VS-VSK.56	UNITS		
Maximum peak reverse and off-state leakage current at V _{RRM} , V _{DRM}	I _{RRM,} I _{DRM}	T _J = 125 °C, gate open circuit	15		mA		
Maximum RMS insulation voltage	V _{INS}	50 Hz	3000 (1 min) 3600 (1 s)		٧		
Maximum critical rate of rise of off-state voltage	dV/dt	$T_J = 125$ °C, linear to 0.67 V_{DRM}	10	00	V/µs		

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL	TEST CONDITIONS	VS-VSK.41	VS-VSK.56	UNITS
Junction operating and storage temperature range		T _J , T _{Stg}		-40 to	+125	°C
Maximum internal thermal resist junction to case per leg	ance,	R _{thJC}	DC operation	0.44	0.35	°C/W
Typical thermal resistance, case to heatsink per module		R _{thCS}	Mounting surface flat, smooth and greased	0	.1	C/VV
	to heatsink		A mounting compound is recommended and the torque should be rechecked after	2	1	
Mounting torque ± 10 %	busbar		a period of 3 hours to allow for the spread of the compound.	3	3	Nm
Approximate weight				7	5	g
Approximate weight				2	.7	oz.
Case style			JEDEC®	AAP G	en 7 (TO-240)	AA)

AR CONDUCTION PER JUNCTION											
DEVICES		SINE HALF	WAVE CO	NDUCTION	١	RI	CTANGUL	AR WAVE C	ONDUCTIO	N	UNITS
DEVICES	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	UNITS
VSK.41	0.110	0.131	0.17	0.23	0.342	0.085	0.138	0.177	0.235	0.345	°C/W
VSK.56	0.088	0.104	0.134	0.184	0.273	0.07	0.111	0.143	0.189	0.275	C/VV

Note

Table shows the increment of thermal resistance R_{thJC} when devices operate at different conduction angles than DC

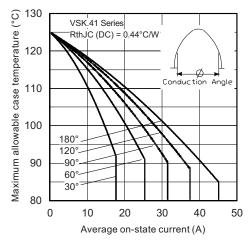


Fig. 1 - Current Ratings Characteristics

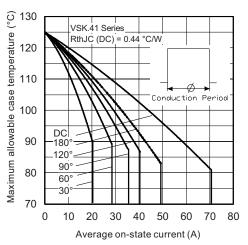


Fig. 2 - Current Ratings Characteristics

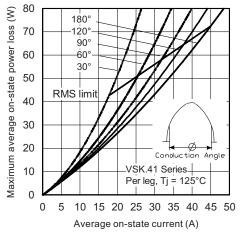


Fig. 3 - On-State Power Loss Characteristics

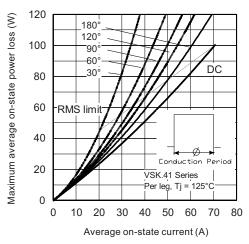
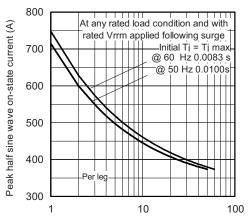


Fig. 4 - On-State Power Loss Characteristics



Number of equal amplitude half cycle current pulses (N)

Fig. 5 - Maximum Non-Repetitive Surge Current

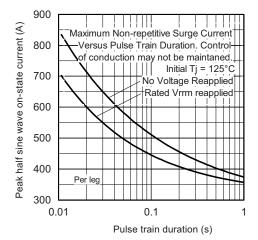


Fig. 6 - Maximum Non-Repetitive Surge Current

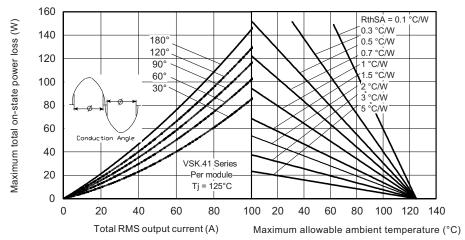


Fig. 7 - On-State Power Loss Characteristics

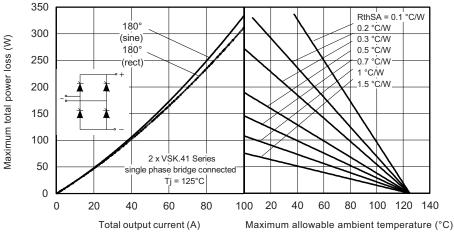


Fig. 8 - On-State Power Loss Characteristics

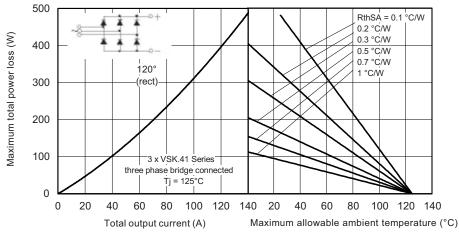


Fig. 9 - On-State Power Loss Characteristics



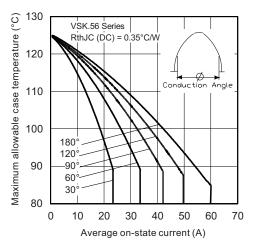


Fig. 10 - Current Ratings Characteristics

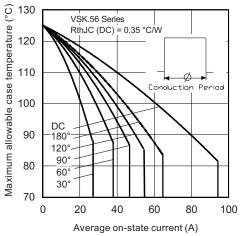


Fig. 11 - Current Ratings Characteristics

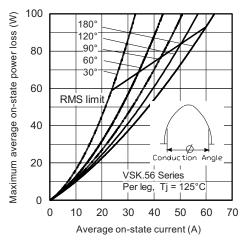


Fig. 12 - On-State Power Loss Characteristics

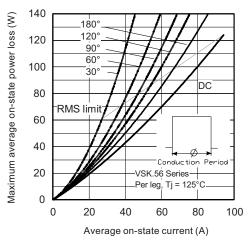
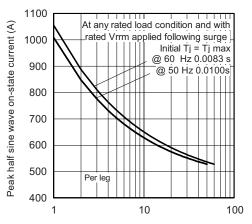


Fig. 13 - On-State Power Loss Characteristics



Number of equal amplitude half cycle current pulses (N)

Fig. 14 - Maximum Non-Repetitive Surge Current

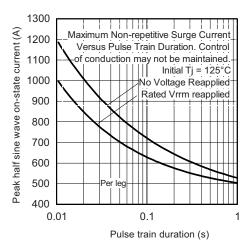


Fig. 15 - Maximum Non-Repetitive Surge Current

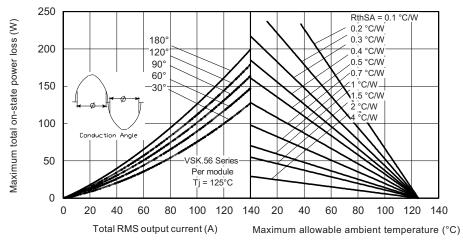


Fig. 16 - On-State Power Loss Characteristics

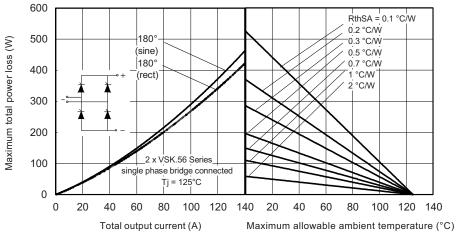


Fig. 17 - On-State Power Loss Characteristics

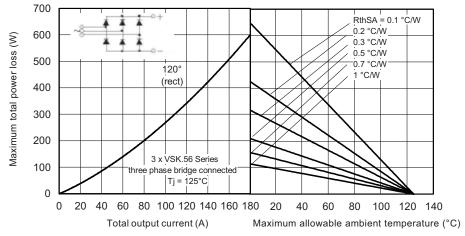


Fig. 18 - On-State Power Loss Characteristics



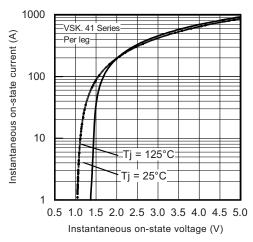


Fig. 19 - On-State Voltage Drop Characteristics

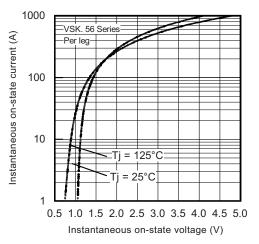


Fig. 20 - On-State Voltage Drop Characteristics

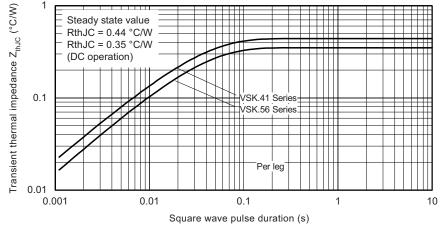


Fig. 21 - Thermal Impedance Z_{thJC} Characteristics

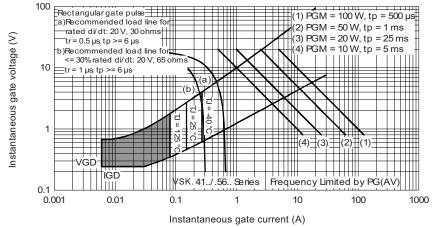
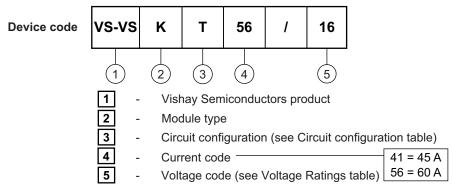


Fig. 22 - Gate Characteristics



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ORDERING INFORMATION TABLE



Note

• To order the optional hardware go to www.vishay.com/doc?95172

CIRCUIT CONFIGURATION	CIRCUIT CONFIGURATION								
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING							
Two SCRs doubler circuit	Т	VSKT (2) (2) (2) (2) (3) (5) (7) (6) (1) (7) (6)							
SCR/diode doubler circuit, positive control	н	VSKH (2) (2) (3) (4) (6) (6)							
SCR/diode doubler circuit, negative control	L	VSKL (2) (2) (2) (3) (6) (7) (6)							
SCR/diode common anodes	N	VSKN 1							

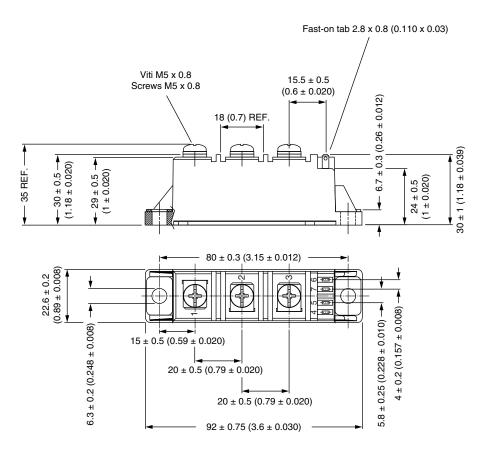
LINKS TO RELATED DOCUMENTS				
Dimensions	www.vishay.com/doc?95368			



Vishay Semiconductors

ADD-A-PAK Generation VII - Thyristor

DIMENSIONS in millimeters (inches)





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